

SN54ALS257A, SN54ALS258A, SN74ALS257A, SN74ALS258A, SN74AS257, SN74AS258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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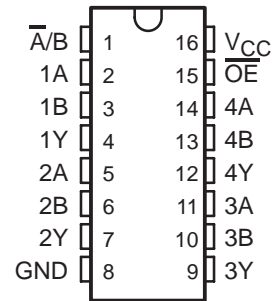
- 3-State Outputs Interface Directly With System Bus
- Provide Bus Interface From Multiple Sources in High-Performance Systems
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

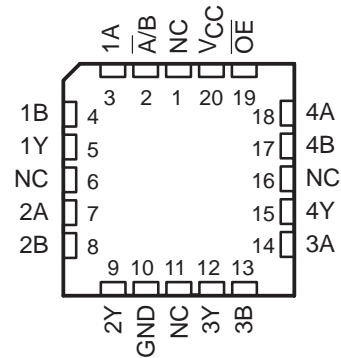
These data selectors/multiplexers are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable (\overline{OE}) input is at a high logic level.

The SN54ALS257A and SN54ALS258A are characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS257A, SN74ALS258A, SN74AS257, and SN74AS258 are characterized for operation from 0°C to 70°C .

SN54ALS257A, SN54ALS258A . . . J PACKAGE
SN74ALS257A, SN74ALS258A, SN74AS257,
SN74AS258 . . . D OR N PACKAGE
(TOP VIEW)



SN54ALS257A, SN54ALS258A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

INPUTS			OUTPUT Y		
\overline{OE}	$\overline{A/B}$	DATA		SN54ALS257A SN74ALS257A SN74AS257	SN54ALS258A SN74ALS258A SN74AS258
		A	B		
H	X	X	X	Z	Z
L	L	L	X	L	H
L	L	H	X	H	L
L	H	X	L	L	H
L	H	X	H	H	L



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

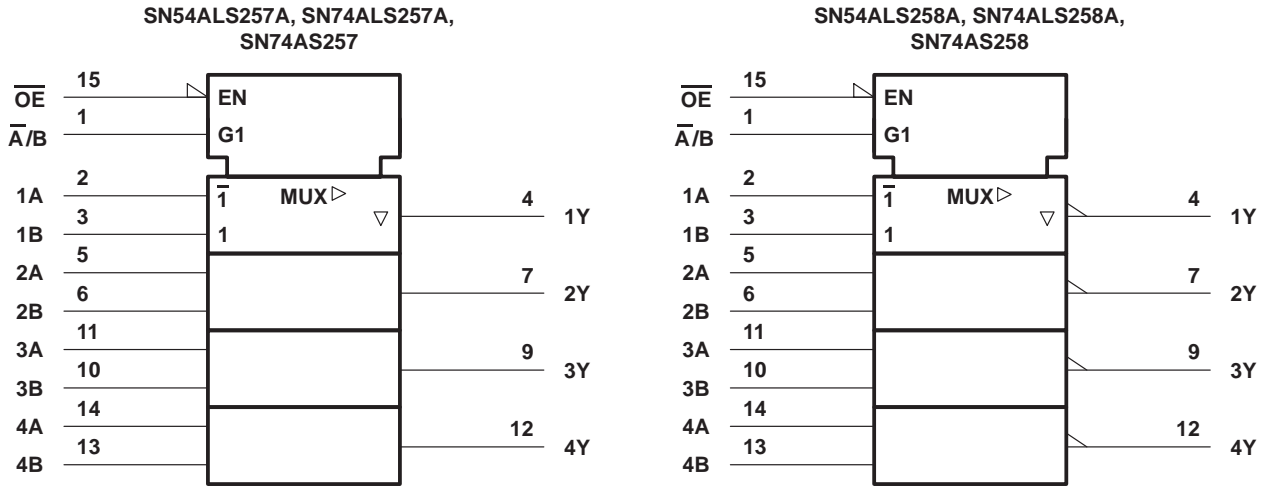
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SN54ALS257A, SN54ALS258A, SN74ALS257A, SN74ALS258A, SN74AS257, SN74AS258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

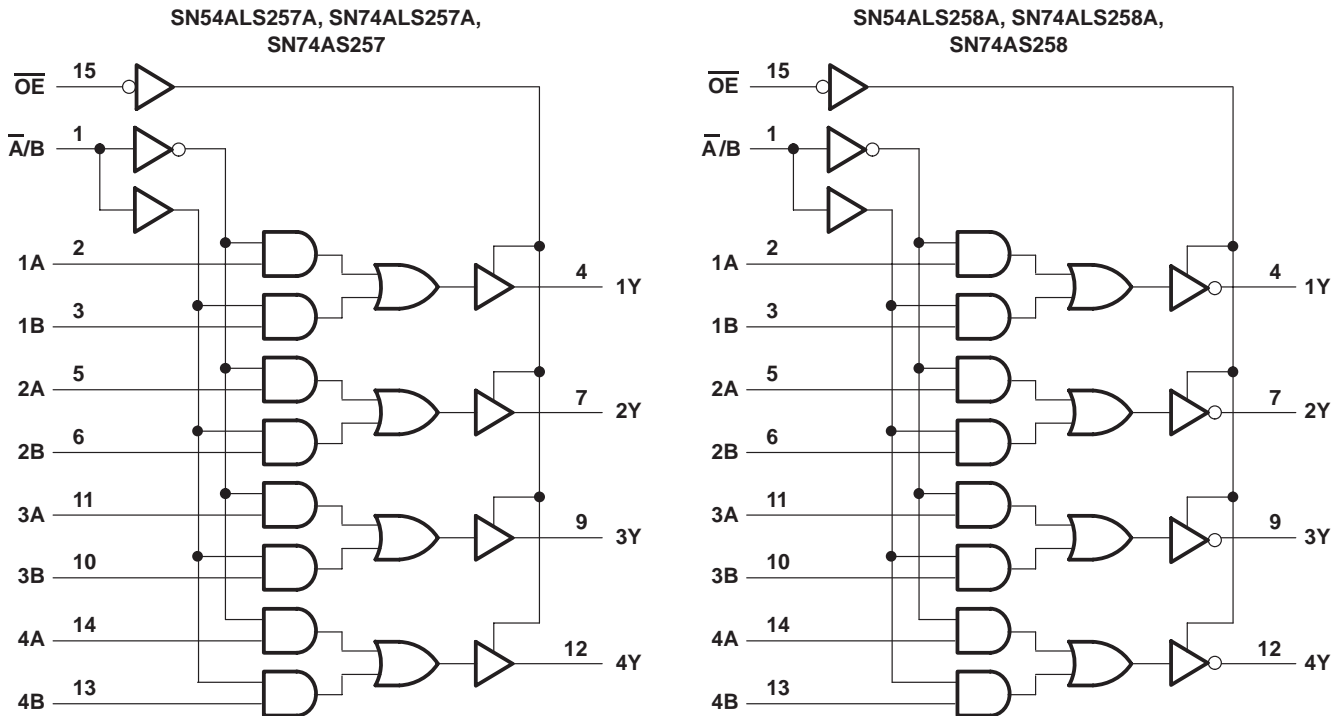
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logic symbols†



† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagrams (positive logic)



Pin numbers shown are for the D, J, and N packages.



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SN54ALS257A, SN54ALS258A, SN74ALS257A, SN74ALS258A, SN74AS257, SN74AS258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 1):	D package
	N package
Operating free-air temperature range, T_A : SN54ALS257A, SN54ALS258A	–55°C to 125°C
SN74ALS257A, SN74ALS258A	0°C to 70°C
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions

	SN54ALS257A SN54ALS258A			SN74ALS257A SN74ALS258A			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.7			0.8	V
I_{OH} High-level output current			–1			–2.6	mA
I_{OL} Low-level output current			12			24	mA
T_A Operating free-air temperature	–55		125	0		70	°C



SN54ALS257A, SN54ALS258A, SN74ALS257A, SN74ALS258A, SN74AS257, SN74AS258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALS257A SN54ALS258A			SN74ALS257A SN74ALS258A			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA		-1.5			-1.5			V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -0.4 mA		V _{CC} -2			V _{CC} -2			V
	V _{CC} = 4.5 V	I _{OH} = -1 mA	2.4	3.3					
		I _{OH} = -2.6 mA				2.4	3.2		
V _{OH}	V _{CC} = 4.5 V	I _{OL} = 12 mA	0.25	0.4		0.25	0.4		V
		I _{OL} = 24 mA				0.35	0.5		
I _{OZH}	V _{CC} = 5.5 V, V _O = 2.7 V		20			20			μA
I _{OZL}	V _{CC} = 5.5 V, V _O = 0.4 V		-20			-20			μA
I _I	V _{CC} = 5.5 V, V _I = 7 V		0.1			0.1			mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V		20			20			μA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.4 V		-0.1			-0.1			mA
I _{O‡}	V _{CC} = 5.5 V, V _O = 2.25 V		-20	-112		-30	-112		mA
I _{CC}	SN54ALS257A, SN74ALS257A	V _{CC} = 5.5 V	Outputs high	3	8	3	6	mA	
			Outputs low	8	12	8	12		
			Outputs disabled	9	14	9	14		
	SN54ALS258A, SN74ALS258A	V _{CC} = 5.5 V	Outputs high	2.5	5	2.5	4		
			Outputs low	7	11	7	11		
			Outputs disabled	8	13	8	13		

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = MIN to MAX§				UNIT
			SN54ALS257A		SN74ALS257A		
			MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Any Y	2	12	2	10	ns
t _{PHL}			2	14	2	12	
t _{PLH}	A̅/B	Any Y	4	21	6	18	ns
t _{PHL}			6	25	6	22	
t _{PZH}	OE̅	Any Y	3	20	4	16	ns
t _{PZL}			4	22	5	18	
t _{PHZ}	OE̅	Any Y	2	12	2	10	ns
t _{PLZ}			2	35	4	15	

§ For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = MIN to MAX†				UNIT
			SN54ALS258A		SN74ALS258A		
			MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Any Y	1	12	2	8	ns
t _{PHL}			2	9	2	7	
t _{PLH}	\bar{A}/B	Any Y	4	28	5	25	ns
t _{PHL}			5	25	6	20	
t _{PZH}	\overline{OE}	Any Y	3	20	4	18	ns
t _{PZL}			5	21	5	18	
t _{PHZ}	\overline{OE}	Any Y	2	12	2	10	ns
t _{PLZ}			3	37	4	18	

† For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Maximum power dissipation at T _A = 55°C (in still air) (see Note 1):	
D package	1.3 W
N package	1.1 W
Operating free-air temperature range, T _A : SN74AS257, SN74AS258	0°C to 70°C
Storage temperature range, T _{stg}	-65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions

		SN74AS257 SN74AS258			UNIT
		MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current			-15	mA
I _{OL}	Low-level output current			48	mA
T _A	Operating free-air temperature	0		70	°C



SN54ALS257A, SN54ALS258A, SN74ALS257A, SN74ALS258A, SN74AS257, SN74AS258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN74AS257 SN74AS258		UNIT		
		MIN	TYP†		MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$	-1.2		V		
V_{OH}	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$, $I_{OH} = -2\text{ mA}$	$V_{CC}-2$		V		
	$V_{CC} = 4.5\text{ V}$, $I_{OH} = -15\text{ mA}$	2.4	3.2			
V_{OL}	$V_{CC} = 4.5\text{ V}$, $I_{OL} = 48\text{ mA}$	0.35	0.5	V		
I_{OZH}	$V_{CC} = 5.5\text{ V}$, $V_O = 2.7\text{ V}$	50		μA		
I_{OZL}	$V_{CC} = 5.5\text{ V}$, $V_O = 0.4\text{ V}$	-50		μA		
I_I	A, B, or \overline{OE}	$V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$		mA		
	$\overline{A/B}$				0.1	0.2
I_{IH}	A, B, or \overline{OE}	$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$		μA		
	$\overline{A/B}$				20	40
I_{IL}	A, B, or \overline{OE}	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$		mA		
	$\overline{A/B}$				-0.5	-1
$I_{O\ddagger}$	$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$	-30	-112	mA		
I_{CC}	SN74AS257	$V_{CC} = 5.5\text{ V}$	Outputs high	12.1	19.7	mA
			Outputs low	19	30.6	
			Outputs disabled	19.7	31.9	
	SN74AS258	$V_{CC} = 5.5\text{ V}$	Outputs high	8.4	13.5	
			Outputs low	15.2	24.6	
			Outputs disabled	15.5	25.2	

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = MIN to MAX†		UNIT
			SN74AS257		
			MIN	MAX	
t _{PLH}	A or B	Any Y	1	5.5	ns
t _{PHL}			1	6	
t _{PLH}	\bar{A}/B	Any Y	2	11	ns
t _{PHL}			2	10	
t _{PZH}	\overline{OE}	Any Y	2	7.5	ns
t _{PZL}			2	9.5	
t _{PHZ}	\overline{OE}	Any Y	1.5	6.5	ns
t _{PLZ}			2	7	

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = MIN to MAX†		UNIT
			SN74AS258		
			MIN	MAX	
t _{PLH}	A or B	Any Y	1	5	ns
t _{PHL}			1	4	
t _{PLH}	\bar{A}/B	Any Y	2	9.5	ns
t _{PHL}			2	10	
t _{PZH}	\overline{OE}	Any Y	2	8	ns
t _{PZL}			2	10	
t _{PHZ}	\overline{OE}	Any Y	1.5	6	ns
t _{PLZ}			2	6.5	

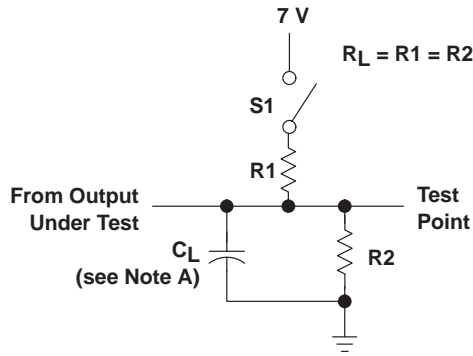
† For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.



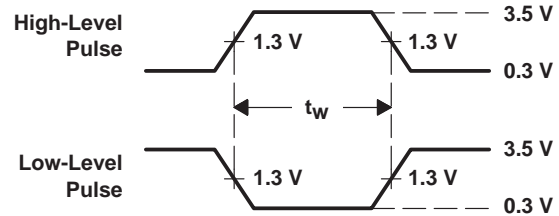
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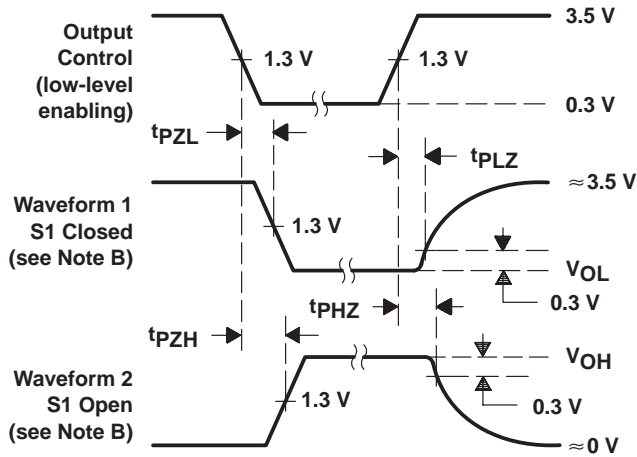
PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



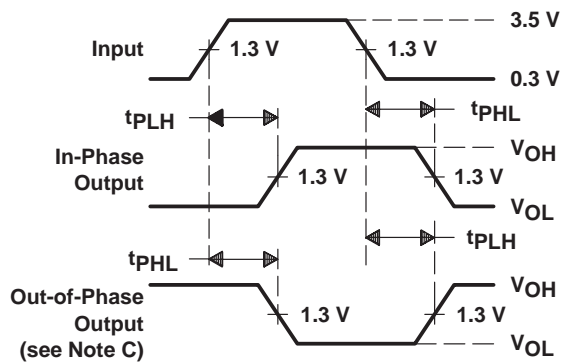
LOAD CIRCUIT
 FOR 3-STATE OUTPUTS



VOLTAGE WAVEFORMS
 PULSE DURATIONS



VOLTAGE WAVEFORMS
 ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS



VOLTAGE WAVEFORMS
 PROPAGATION DELAY TIMES

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-88626012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8862601EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
5962-8862601FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
85097012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
8509701EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
8509701FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
SN54ALS257AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN74ALS257AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS257ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS257ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS257ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS257ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS257ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS257AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS257ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS257ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS257ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS257ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS258AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS258ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS258ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74ALS258ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS258ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS258ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS258AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS258ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS257D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS257DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS257DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS257N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS257NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS257NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS257NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS257NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS258DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS258DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS258DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS258N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS258NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SNJ54ALS257AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS257AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS257AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS258AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SNJ54ALS258AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS258AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54ALS257A, SN54ALS258A, SN74ALS257A, SN74ALS258A :

● Catalog: [SN74ALS257A](#), [SN74ALS258A](#)

● Military: [SN54ALS257A](#), [SN54ALS258A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS257ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS257ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ALS258ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AS257NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS258DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS257ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS257ANSR	SO	NS	16	2000	367.0	367.0	38.0
SN74ALS258ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AS257NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74AS258DR	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

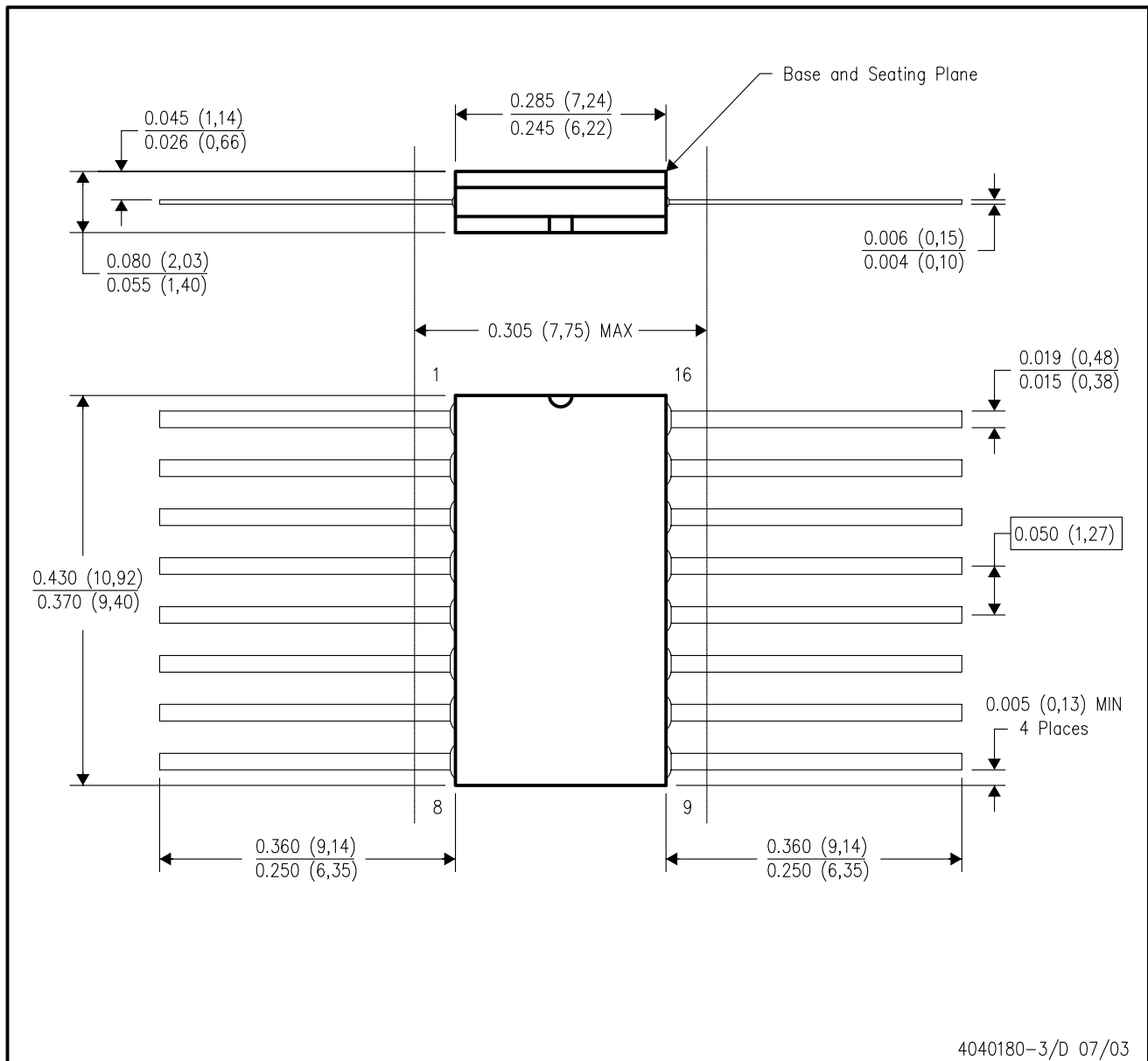


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - (C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - (D) The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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